

Product / Process Change Notice

No.: Z200-PCN-DM201901-01-A

Date: January 02, 2019

Change Title : <u>2Gb (256Mbx8 and 128Mbx16) DDR3/DDR3L technology migration from 38nm to 25nm for</u> <u>Commercial and Industrial grade</u>

Change Classification: ☑ Major Minor with customer notification Change item : ☑ Design Raw Material Wafer FAB Assembly Testing Packing Others

Affected Product(s) :

Please refer to Table 1 in details.

Description of Change(s)

Technology migration (38nm to 25nm) for 2Gb DDR3/DDR3L Commercial and Industrial grade.

Reason for Change(s) :

According to Winbond product roadmap, launch new 2Gb DDR3/DDR3L Commercial and Industrial grade with 25nm technology.

Impact of Change(s) : (positive & negative)

Form: No Change

Fit : No Change (Refer to attachment I)

Function : No Concern (The function is compatible between 38nm and 25nm, refer to attachment II)

Reliability : No Concern (The reliability test pass, refer to attachment III)

Hazardous Substances: No Concern (Please refer to attachment IV)

Qualification Plan/ Results :

Base on Winbond Reliability report, the Commercial/Industrial grade meet Winbond criteria and no quality concern (refer to attachment III in detail).

Implementation Plan :

Commercial/Industrial grade product launch date of the 25nm	256Mb x8 and 128	8Mb x16 2Gb DDR	3/ DDR3L: Dec 25,
2018.			

Proposed ship date of the 25nm 256Mb x8 and 128Mb x16 2Gb DDR3/DDR3L Commercial/Industrial grade: Apr 01, 2019.

The follow-up disposition of 38nm 256Mb x8 and 128Mb x16 2Gb DDR3/DDR3L Commercial/Industrial grade:

1) The date of Last-buy orders for the 38nm 256Mb x8 and 128Mb x16 2Gb DDR3/DDR3L Commercial/Industrial grade: Jul 01, 2019.

2) The last shipment date of the 38nm 256Mb x8 and 128Mb x16 2Gb DDR3/DDR3L Commercial/Industrial grade: Oct 01, 2020.

Date Code: _____ onward

Lot No: _____ onward

Proposed first ship date: April 01, 2019

Originator: (QA)	Hybuang	Approval: (QA Dept. Manager)	ytt Cheng	Approval: (QRA Director)	Chin



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Contact for Questions & Concerns	Address : <u>No. 8,Keya 1st Rd., Daya Dist., Central Taiwan Science Park, Taichung</u> <u>City 42881,Taiwan</u>		
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Customer Comments:

Note: Please sign this notice, and return to Winbond contact within **30** days. If no response is received within **30** days, this Change Request will be assumed to meet your approval.

Major change: D Approval	Disapproval	Conditional Approval :
Minor change with customer notif	ication: Recognition	1
Comment:		
Date:		
Dept. name:		
Person in charge:		



W632GG6MB-07	W632GG6MB12J	W632GU6MB11I	W632GG8MB09I	W632GU8MB09I
W632GG6MB-08	W632GG6MB-15	W632GU6MB11J	W632GG8MB-11	W632GU8MB-11
W632GG6MB-09	W632GG6MB15I	W632GU6MB-12	W632GG8MB11I	W632GU8MB11I
W632GG6MB09I	W632GG6MB15J	W632GU6MB12I	W632GG8MB11J	W632GU8MB-12
W632GG6MB09J	W632GU6MB-08	W632GU6MB12J	W632GG8MB-12	W632GU8MB12I
W632GG6MB-11	W632GU6MB-09	W632GU6MB-15	W632GG8MB12I	W632GU8MB12J
W632GG6MB11I	W632GU6MB09I	W632GU6MB15I	W632GG8MB-15	W632GU8MB-15
W632GG6MB-12	W632GU6MB09J	W632GU6MB15J	W632GG8MB15I	W632GU8MB15I
W632GG6MB12I	W632GU6MB-11	W632GG8MB-09	W632GU8MB-09	

Table 1. The affected part no are list below.